

# 2N7000 / 2N7002 / NDS7002A N-Channel Enhancement Mode Field Effect Transistor

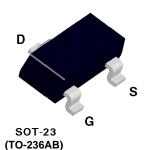
# **General Description**

These N-Channel enhancement mode field effect transistors are produced using Fairchild's proprietary, high cell density, DMOS technology. These products have been designed to minimize on-state resistance while provide rugged, reliable, and fast switching performance. They can be used in most applications requiring up to 400mA DC and can deliver pulsed currents up to 2A. These products are particularly suited for low voltage, low current applications such as small servo motor control, power MOSFET gate drivers, and other switching applications.

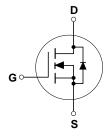
#### **Features**

- High density cell design for low R<sub>DS(ON)</sub>.
- Voltage controlled small signal switch.
- Rugged and reliable.
- High saturation current capability.





2N7002/NDS7002A



### Absolute Maximum Ratings T = 25°C unless otherwise noted

Symbol	Parameter	2N7000	2N7002	NDS7002A	Units	
V <sub>DSS</sub>	Drain-Source Voltage	60		V		
$V_{DGR}$	Drain-Gate Voltage ( $R_{GS} \le 1 M\Omega$ )	60			V	
$V_{GSS}$	Gate-Source Voltage - Continuous	±20			V	
	- Non Repetitive (tp < 50μs)	±40				
I <sub>D</sub>	Maximum Drain Current - Continuous	200	115	280	mA	
	- Pulsed	500	800	1500	7	
P <sub>D</sub>	Maximum Power Dissipation	400	200	300	mW	
	Derated above 25°C	3.2	1.6	2.4	mW/°C	
T <sub>J</sub> ,T <sub>STG</sub>	Operating and Storage Temperature Range	-55 to 150 -65 to 150		°C		
T <sub>L</sub>	Maximum Lead Temperature for Soldering Purposes, 1/16" from Case for 10 Seconds	300		°C		
THERMA	L CHARACTERISTICS				•	
R <sub>θJA</sub>	Thermal Resistance, Junction-to-Ambient	312.5	625	417	°C/W	

Symbol	Parameter	Conditions		Type	Min	Тур	Max	Units
OFF CHA	RACTERISTICS							
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, I_{D} = 10 \mu\text{A}$		All	60			V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 48 V, V <sub>GS</sub> = 0 V		2N7000			1	μΑ
			T <sub>J</sub> =125°C				1	mA
		$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$		2N7002			1	μΑ
			T <sub>J</sub> =125°C	NDS7002A			0.5	mA
I <sub>GSSF</sub>	Gate - Body Leakage, Forward	$V_{GS} = 15 \text{ V}, V_{DS} = 0 \text{ V}$		2N7000			10	nA
		$V_{GS} = 20 \text{ V}, V_{DS} = 0 \text{ V}$		2N7002 NDS7002A			100	nA
I <sub>GSSR</sub>	Gate - Body Leakage, Reverse	$V_{GS} = -15 \text{ V}, V_{DS} = 0 \text{ V}$		2N7000			-10	nA
		$V_{GS} = -20 \text{ V}, V_{DS} = 0 \text{ V}$		2N7002 NDS7002A			-100	nA
ON CHAP	RACTERISTICS (Note 1)							
$V_{\text{GS(th)}}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$ , $I_D = 1 \text{ mA}$		2N7000	0.8	2.1	3	V
		$V_{DS} = V_{GS}, I_{D} = 250 \mu A$		2N7002 NDS7002A	1	2.1	2.5	
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance	$V_{GS} = 10 \text{ V}, I_{D} = 500 \text{ mA}$		2N7000		1.2	5	Ω
			T <sub>J</sub> =125°C			1.9	9	
		$V_{GS} = 4.5 \text{ V}, I_{D} = 75 \text{ mA}$				1.8	5.3	
		$V_{GS} = 10 \text{ V}, I_{D} = 500 \text{ mA}$		2N7002		1.2	7.5	
			T <sub>J</sub> =100°C			1.7	13.5	
		$V_{GS} = 5.0 \text{ V}, I_{D} = 50 \text{ mA}$				1.7	7.5	
			$T_{J} = 100C$			2.4	13.5	
		$V_{GS} = 10 \text{ V}, I_{D} = 500 \text{ mA}$		NDS7002A		1.2	2	
			T <sub>J</sub> =125°C			2	3.5	
		$V_{GS} = 5.0 \text{ V}, I_{D} = 50 \text{ mA}$				1.7	3	
			T <sub>J</sub> =125°C			2.8	5	
V <sub>DS(ON)</sub>	Drain-Source On-Voltage	$V_{GS} = 10 \text{ V}, \ I_{D} = 500 \text{ mA}$ $V_{GS} = 4.5 \text{ V}, \ I_{D} = 75 \text{ mA}$		2N7000		0.6	2.5	V
						0.14	0.4	
		$V_{GS} = 10 \text{ V}, I_{D} = 500 \text{mA}$		2N7002		0.6	3.75	
		$V_{GS} = 5.0 \text{ V}, I_D = 50 \text{ mA}$				0.09	1.5	
		$V_{GS} = 10 \text{ V}, I_{D} = 500 \text{mA}$		NDS7002A		0.6	1	
		$V_{GS} = 5.0 \text{ V}, I_{D} = 50 \text{ mA}$				0.09	0.15	

Symbol	Parameter	Conditions	Туре	Min	Тур	Max	Units
ON CHAI	RACTERISTICS Continued (Note 1)	•					•
I <sub>D(ON)</sub>	On-State Drain Current	$V_{GS} = 4.5 \text{ V}, \ V_{DS} = 10 \text{ V}$	2N7000	75	600		mA
		$V_{GS} = 10 \text{ V}, V_{DS} \ge 2 V_{DS(on)}$	2N7002	500	2700		
		$V_{GS} = 10 \text{ V}, V_{DS} \ge 2 V_{DS(on)}$	NDS7002A	500	2700		
g <sub>FS</sub>	Forward Transconductance	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 200 mA	2N7000	100	320		mS
		$V_{DS} \ge 2 V_{DS(on)}, I_{D} = 200 \text{ mA}$	2N7002	80	320		
		$V_{DS} \ge 2 V_{DS(on)}$ , $I_D = 200 \text{ mA}$	NDS7002A	80	320		
DYNAMIC	CHARACTERISTICS						
C <sub>iss</sub>	Input Capacitance	$V_{DS} = 25 \text{ V}, \ V_{GS} = 0 \text{ V}, $ f = 1.0 MHz	All		20	50	pF
C <sub>oss</sub>	Output Capacitance	f = 1.0 MHz	All		11	25	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		All		4	5	pF
t <sub>on</sub>	Turn-On Time	$V_{DD} = 15 \text{ V}, R_{L} = 25 \Omega,$ $I_{D} = 500 \text{ mA}, V_{GS} = 10 \text{ V},$ $R_{GEN} = 25$	2N7000			10	ns
		$\begin{split} &V_{DD} = 30 \; V, \; R_{L} = 150 \; \Omega, \\ &I_{D} = 200 \; mA, \; V_{GS} = 10 \; V, \\ &R_{GEN} = 25 \; \Omega \end{split}$	2N7002 NDS7002A			20	
t <sub>off</sub>	Turn-Off Time	$V_{DD} = 15 \text{ V}, R_{L} = 25 \Omega,$ $I_{D} = 500 \text{ mA}, V_{GS} = 10 \text{ V},$ $R_{GEN} = 25$	2N7000			10	ns
		$\begin{split} &V_{\text{DD}} = 30 \text{ V}, \text{ R}_{\text{L}} = 150 \Omega, \\ &I_{\text{D}} = 200 \text{ mA}, V_{\text{GS}} = 10 \text{ V}, \\ &R_{\text{GEN}} = 25 \Omega \end{split}$	2N7002 NDS7002A			20	
DRAIN-S	OURCE DIODE CHARACTERISTICS	S AND MAXIMUM RATINGS					
I <sub>s</sub>	Maximum Continuous Drain-Source Diode Forward Current		2N7002			115	mA
			NDS7002A			280	
I <sub>SM</sub>	Maximum Pulsed Drain-Source Diode Forward Current		2N7002			0.8	Α
			NDS7002A			1.5	
V <sub>SD</sub>	Drain-Source Diode Forward	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 115 mA (Note 1)	2N7002		0.88	1.5	V
	Voltage	V <sub>GS</sub> = 0 V, I <sub>S</sub> = 400 mA (Note 1)	NDS7002A		0.88	1.2	7

Note: 1. Pulse Test: Pulse Width ≤ 300µs, Duty Cycle ≤ 2.0%.

# **Typical Electrical Characteristics**

# 2N7000 / 2N7002 / NDS7002A

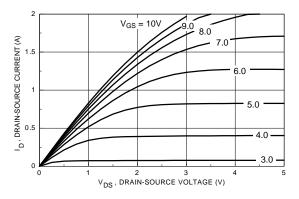


Figure 1. On-Region Characteristics

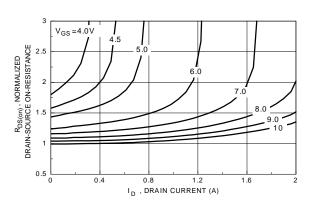


Figure 2. On-Resistance Variation with Gate Voltage and Drain Current

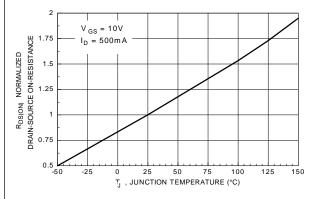


Figure 3. On-Resistance Variation with Temperature

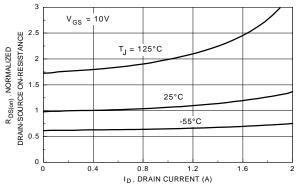


Figure 4. On-Resistance Variation with Drain Current and Temperature

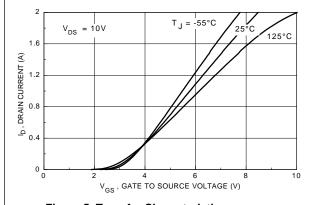


Figure 5. Transfer Characteristics

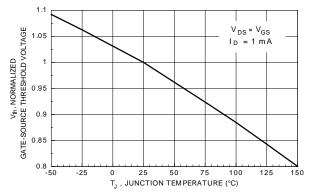


Figure 6. Gate Threshold Variation with Temperature

# **Typical Electrical Characteristics (continued)**

# 2N7000 / 2N7002 /NDS7002A

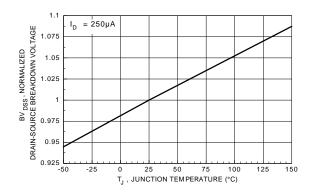
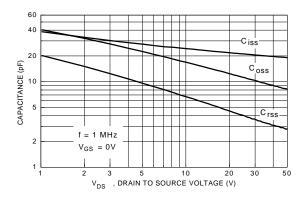


Figure 7. Breakdown Voltage Variation with Temperature

Figure 8. Body Diode Forward Voltage Variation with



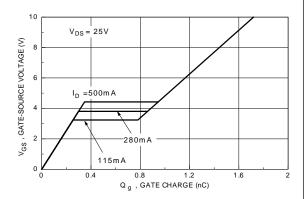
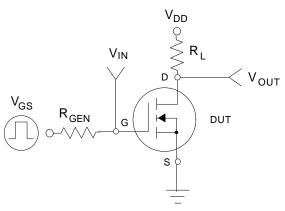


Figure 9. Capacitance Characteristics

Figure 10. Gate Charge Characteristics



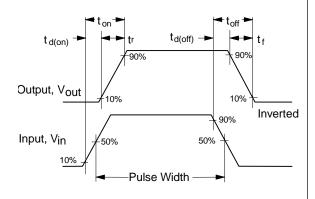
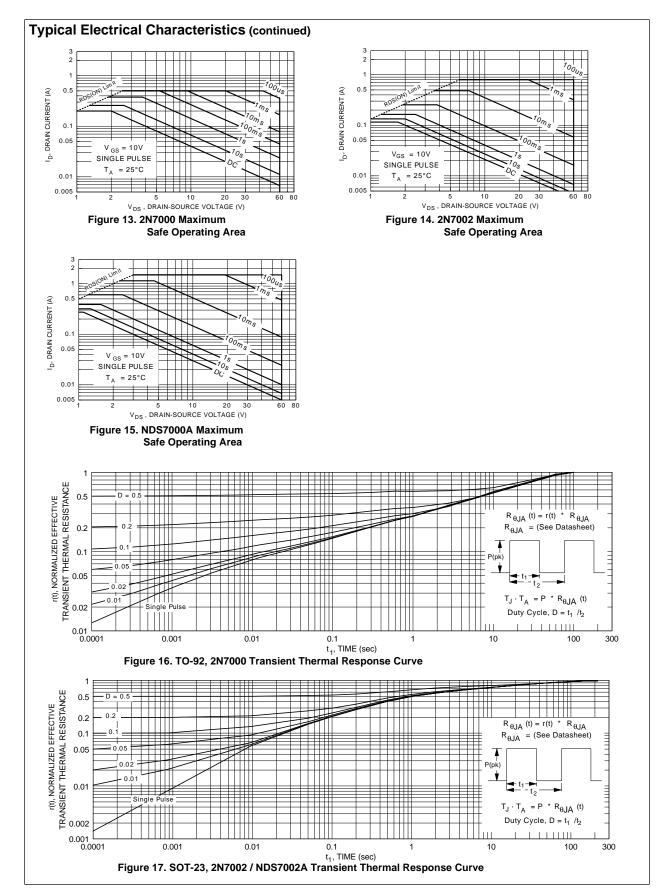


Figure 11.

Figure 12. Switching Waveforms



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